

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5852712

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOMEMATSU ABE	12/03/2019
RECEIVING PARTY DATA	
Name:	NICHIWA CO., LTD.
Street Address:	528-1, OZUWA,
City:	NUMAZU-SHI, SHIZUOKA
State/Country:	JAPAN
Postal Code:	410-0873
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16619766
CORRESPONDENCE DATA	
Fax Number:	(703)518-5499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	703-684-1111
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Correspondent Name:	KANESAKA BERNER AND PARTNERS LLP
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ATTORNEY DOCKET NUMBER:	SMP-008
NAME OF SUBMITTER:	MANABU KANESAKA
SIGNATURE:	/Manabu KANESAKA/
DATE SIGNED:	12/05/2019
Total Attachments: 1	
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ASSIGNMENT

For value received, I, Tomematsu ABE having post office address at c/o NICHIIWA CO., LTD., 528-1, Ozuwa, Numazu-shi, Shizuoka 410-0873, Japan hereby sell, assign and transfer to NICHIIWA CO., LTD. a corporation existing under the laws of Japan located at 528-1, Ozuwa, Numazu-shi, Shizuoka 410-0873, Japan and its successors, assigns, and legal representatives the entire right, title, and interest for all countries including the United States of America, in and to certain inventions relating to PACKAGING MATERIAL, PACKAGING BAG, PACKAGED ARTICLE, AND PACKAGING METHOD described in application for Letters Patent of the United States, executed by me/us on this date, and all patents which may be granted therefor, and all divisions, reissues, continuations and extensions thereof, and authorize and request the Commissioner of Patents and Trademarks to issue all patents on said improvements or resulting therefrom to said Company as assignee of the entire interest, and covenant that I/We have full right so to do, and agree that I/We will communicate to said Company or its representatives any facts known to me/us respecting said improvements and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid said Company, its successors, assigns, and nominees, to obtain and enforce proper protection for said invention in the United States.

Signature

Tomematsu Abe

Date

Dec 3, 2019

Tomematsu ABE